

INFINEONS POWER MODULE STRUCTURE ANALYSIS REPORT

February 2020. LTEC Corporation released a detailed structure analysis reports of the Infineon power module used in the Hyundai automotive IONIQ PHEV.



Module

Product overview

IGBT power module with double-sided cooling structure, components embedded in the PCB, and Direct Bonded Copper (DBC) at the top and bottom layers of the PCB to enhance heat removal.

Report content

The 94-page report includes:

- Structural details: Module appearance, X-ray observations.
- Layer-by-layer analysis including partial circuit schematic, terminal connection method, and other details of interest related to manufacturing technology.
- Module cross section analysis: SEM-EDX analysis, resin component analysis by Fourier transform infra-red spectroscopy analysis (FT-IR).
- Die cross-sectional analysis (transistor and die edge): Semiconductor layers, circuit schematic, and die layout confirmation.

Structure analysis report: \$7,000

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